Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **IN A**
2. **GND**
3. **IN B**
4. **N. OUT B**
5. **VS**
6. **N. OUT A**

**.056”**

**.063”**

**3**

**2**

**1**

**4**

**6**

**5**

**4428A**

**MASK**

**REF**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential:**

**Mask Ref: 4428A**

**APPROVED BY: DK DIE SIZE .056” X .063” DATE: 8/26/21**

**MFG: MICREL THICKNESS .025” P/N: MIC4428**

**DG 10.1.2**

#### Rev B, 7/1